Power MOSFET 40 V, 0.7 mΩ, 378 A, Single N–Channel

Features

- Small Footprint (5x6 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- NVMFS5C404NWF Wettable Flank Option for Enhanced Optical Inspection
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant



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| V _{(BR)DSS} | R _{DS(ON)} MAX | I _D MAX | |
|----------------------|-------------------------|--------------------|--|
| 40 V | 0.7 mΩ @ 10 V | 378 A | |

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted) Parameter Symbol Value Unit Drain-to-Source Voltage VDSS 40 V Gate-to-Source Voltage V_{GS} ±20 V Continuous Drain $T_{\rm C} = 25^{\circ}{\rm C}$ 378 A I_D Current R_{0JC} $T_C = 100^{\circ}C$ 267 (Notes 1, 3) Steadv State Power Dissipation $T_C = 25^{\circ}C$ PD 200 W $R_{\theta JC}$ (Note 1) $T_{C} = 100^{\circ}C$ 100 $T_A = 25^{\circ}C$ Continuous Drain I_D 53 А Current R_{0JA} $T_A = 100^{\circ}\overline{C}$ 37 (Notes 1, 2, 3) Steady State Power Dissipation W $T_A = 25^{\circ}C$ P_D 3.9 $R_{\theta JA}$ (Notes 1 & 2) $T_A = 100^{\circ}\overline{C}$ 1.9 Pulsed Drain Current $T_A = 25^{\circ}C, t_p = 10 \ \mu s$ 900 А IDM **Operating Junction and Storage Temperature** T_J, T_{stg} -55 to °C +175Source Current (Body Diode) 191 Α Is Single Pulse Drain-to-Source Avalanche 907 mJ E_{AS} Energy $(I_{L(pk)} = 38 \text{ A})$ Lead Temperature for Soldering Purposes T 260 °C (1/8" from case for 10 s)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

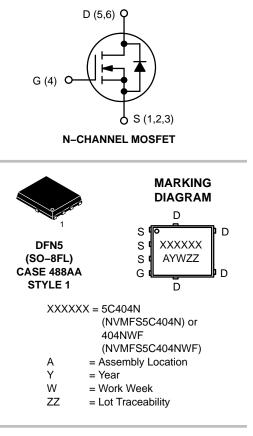
THERMAL RESISTANCE MAXIMUM RATINGS

| Parameter | Symbol | Value | Unit |
|---|---------------------|-------|------|
| Junction-to-Case - Steady State | $R_{	ext{	heta}JC}$ | 0.75 | °C/W |
| Junction-to-Ambient - Steady State (Note 2) | R_{\thetaJA} | 39 | |

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

2. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.

3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.



ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

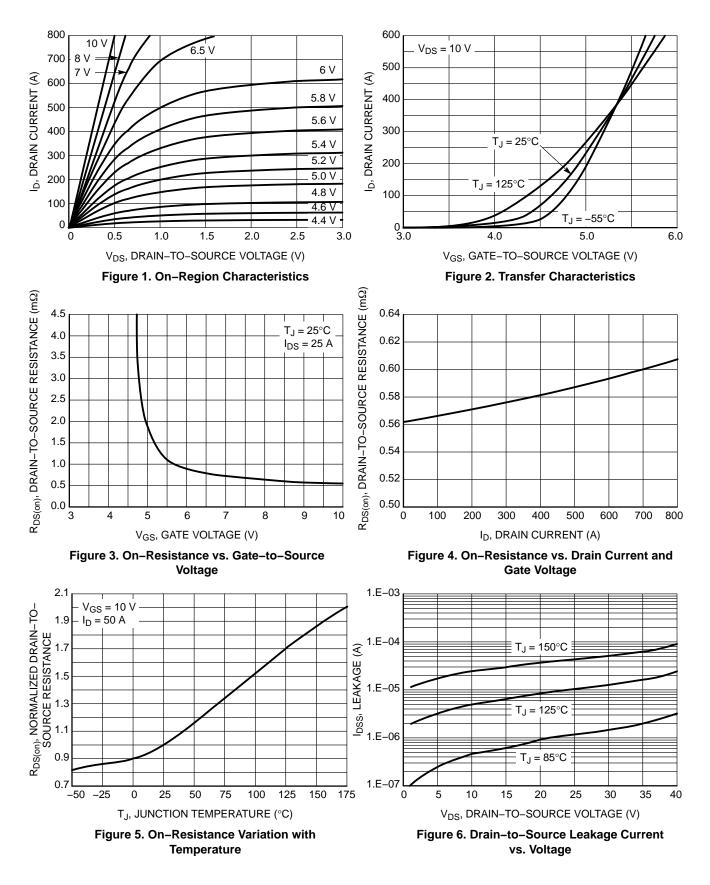
ELECTRICAL CHARACTERISTICS (T_J = 25° C unless otherwise specified)

| Parameter | Symbol | Test Condition | | Min | Тур | Max | Unit |
|--|--|--|------------------------|-----|------|-----|-------|
| OFF CHARACTERISTICS | - | | | | | | |
| Drain-to-Source Breakdown Voltage | V _{(BR)DSS} | $V_{GS} = 0 V, I_D = 250 \mu A$ | | 40 | | | V |
| Drain-to-Source Breakdown Voltage Temperature Coefficient | V _{(BR)DSS} / T _J | | | | 19.7 | | mV/°C |
| Zero Gate Voltage Drain Current | I _{DSS} | $V_{GS} = 0 V,$ | T _J = 25 °C | | | 10 | |
| | $V_{DS} = 40 V$ $T_{J} = 125$ | T _J = 125°C | | | 250 | μA | |
| Gate-to-Source Leakage Current | I _{GSS} | V _{DS} = 0 V, V _{GS} = 20 V | | | | 100 | nA |
| ON CHARACTERISTICS (Note 4) | | | | | | | |
| Gate Threshold Voltage | V _{GS(TH)} | $V_{GS} = V_{DS}, I_D = 250 \ \mu A$ | | 2.0 | | 4.0 | V |
| Threshold Temperature Coefficient | V _{GS(TH)} /T _J | | | | -6.2 | | mV/°C |
| Drain-to-Source On Resistance | R _{DS(on)} | V _{GS} = 10 V | I _D = 50 A | | 0.57 | 0.7 | mΩ |
| Forward Transconductance | 9FS | V _{DS} =15 V, I _D = 50 A | | | 210 | | S |
| CHARGES, CAPACITANCES & GATE RE | SISTANCE | | | | | | |
| Input Capacitance | C _{ISS} | V _{GS} = 0 V, f = 1 MHz, V _{DS} = 25 V | | | 8400 | | pF |
| Output Capacitance | C _{OSS} | | | | 4600 | | |
| Reverse Transfer Capacitance | C _{RSS} | | | | 120 | | |
| Total Gate Charge | Q _{G(TOT)} | V_{GS} = 10 V, V_{DS} = 20 V; I_{D} = 50 A | | | 128 | | |
| Threshold Gate Charge | Q _{G(TH)} | V _{GS} = 10 V, V _{DS} = 20 V; I _D = 50 A | | | 22 | | nC |
| Gate-to-Source Charge | Q _{GS} | | | | 35 | | |
| Gate-to-Drain Charge | Q _{GD} | | | | 26 | | |
| Plateau Voltage | V _{GP} | | | | 4.3 | | V |
| SWITCHING CHARACTERISTICS (Note 5 | 5) | | | | | - | |
| Turn-On Delay Time | t _{d(ON)} | V_{GS} = 10 V, V_{DS} = 20 V, I _D = 50 A, R _G = 2.5 Ω | | | 16 | | - ns |
| Rise Time | tr | | | | 113 | | |
| Turn–Off Delay Time | t _{d(OFF)} | | | | 77 | | |
| Fall Time | t _f | | | | 109 | | |
| DRAIN-SOURCE DIODE CHARACTERIS | TICS | | | - | | - | - |
| Forward Diode Voltage | V _{SD} | $V_{GS} = 0 V,$ $I_{S} = 50 A$ | $T_J = 25^{\circ}C$ | | 0.76 | 1.2 | V |
| | | | T _J = 125°C | | 0.63 | | |
| Reverse Recovery Time | t _{RR} | V _{GS} = 0 V, dIS/dt = 100 A/µs, I _S = 50 A | | | 96 | | ns |
| Charge Time | ta | | | | 49 | | |
| Discharge Time | t _b | | | | 47 | | |
| Reverse Recovery Charge | Q _{RR} | | | | 189 | | nC |

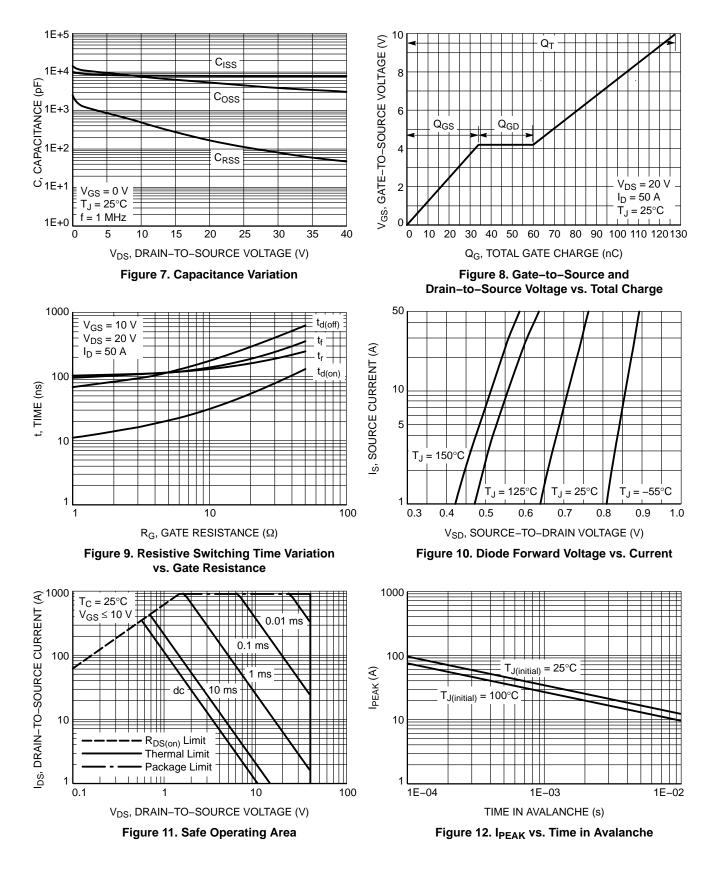
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Pulse Test: pulse width $\leq 300 \ \mu$ s, duty cycle $\leq 2\%$.

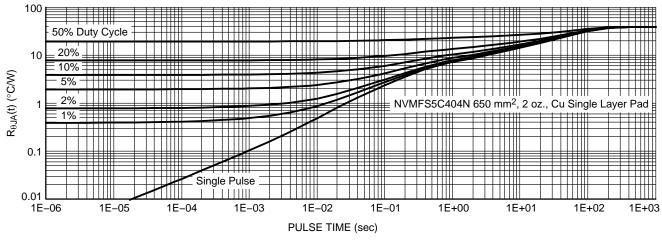
5. Switching characteristics are independent of operating junction temperatures.

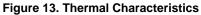
TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS





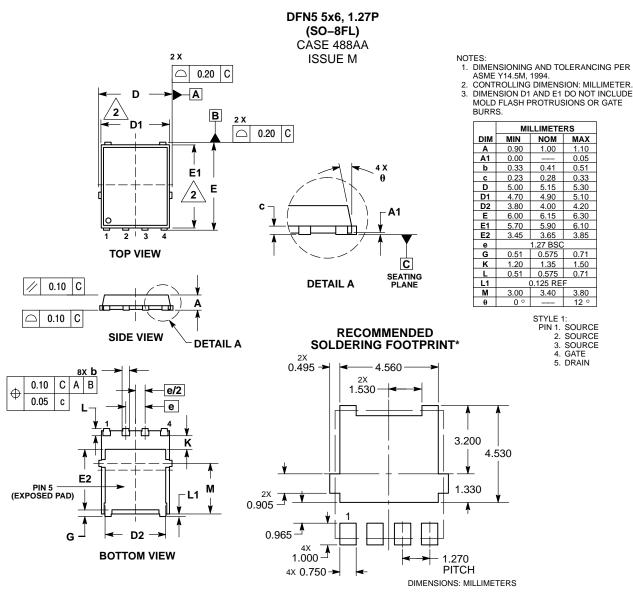


DEVICE ORDERING INFORMATION

| Device | Marking | Package | Shipping [†] |
|--------------------|---------|------------------------------------|-----------------------|
| NVMFS5C404NT1G | 5C404N | DFN5 (Pb–Free) | 1500 / Tape & Reel |
| NVMFS5C404NWFT1G | 404NWF | DFN5 (Pb–Free, Wettable Flanks) | 1500 / Tape & Reel |
| NVMFS5C404NT3G | 5C404N | DFN5 (Pb–Free) | 5000 / Tape & Reel |
| NVMFS5C404NWFT3G | 404NWF | DFN5 (Pb–Free, Wettable Flanks) | 5000 / Tape & Reel |
| NVMFS5C404NAFT1G | 5C404N | DFN5 (Pb–Free) | 1500 / Tape & Reel |
| NVMFS5C404NWFAFT1G | 404NWF | DFN5 (Pb-Free, Wettable Flanks) | 1500 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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